Y0019

P-Channel Enhancement Mode MOSFET

-30V(VDS) / ±20V(VGS) / -10A(ID)

Rev0.5

Wafer Specification

1. Order Information

Part No.	Description	Gross die / per 8" wafer
Y0019	**-30V(V_{DS}) / ±20V(V_{GS}) / -10A(I_D)** **P-Channel Enhancement Mode MOSFET**	19,508

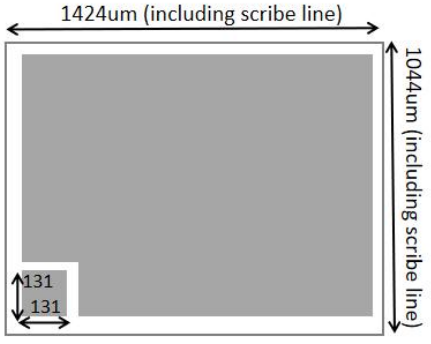
2. Mechanical Data

Nominal Back Metal Composition, Thickness	Ti-Ni-Ag (13kÅ)
Nominal Front Metal Composition, Thickness	AlCu (4μm)
Wafer Diameter	200mm, with 010 notch
Wafer Thickness	150μm±10μm
Scribe Line Width	60μm
Passivation	SRO+SiN

3. Key Electrical Characteristics of Die（at Tj = 25 °C, unless otherwise specified)

Parameter	Description	Min.	Typ.	Max.	Unit	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-30			V	V_{GS}=0V, I_D=-250μA
$I_{D(Device\ Ref)}$	Continuous Drain Current			-10	A	T_J=25℃
$R_{DS(on)}$(CP)	Static Drain-to-Source On-Resistance		15	23	mΩ	V_{GS}=-10V, I_D=-1A
			21	31	mΩ	V_{GS}=-4.5V, I_D=-1A
$R_{DS(on)}$(FT)	Static Drain-to-Source On-Resistance		16	24	mΩ	V_{GS}=-10V, I_D=-10A
			22	32	mΩ	V_{GS}=-4.5V, I_D=-5A
$V_{GS(th)}$	Gate Threshold Voltage	-1.0	-1.6	-2.5	V	V_{DS}=V_{GS}, I_D=-250μA
I_{DSS}	Drain-to-Source Leakage Current			-1	μA	V_{DS}=-30V, V_{GS}=0V
I_{GSS}	Gate-to-Source Leakage Current			±100	nA	V_{GS}=±20V, V_{DS}=0V
T_J, T_{STG}	Operating and Storage Temperature	-55℃ to 150℃ Max				

4. Die Outline



Die Size: 1424μm x 1044μm (including scribe line)

Gate: 131μm × 131μm

For SOP-8 package

Suggest Bonding wire:

Gate: 1×42 μm Cu

Source: 14× 42 μm CU